

AMENDMENTS

In the Specification

Please replace the paragraph beginning on Page 5, line 18 with the following amended paragraph:

Once the processor and socket connectors are compressed together, movement of load plate 12 to an open position distal socket 18 exposes processor 16 for lifting out of socket 18. However, attempts to lift processor 16 by hand introduce rotational and drag forces that tend to damage the connectors. One type of processor extraction device that limits the risk of damage to connectors is an adhesive 28 disposed between load plate 12 and processor 16. Adhesive 28 couples processor 16 to load plate 12, such as at the heat spreader located at the outer circumference of processor 12 16, so that opening load plate 12 raises processor 16 away from socket 18 to allow manipulation of processor 16 by hand with reduced risk of damaging contact between the socket and processor land grid array connectors. Coupling of adhesive 28 is aided by compression of load plate 12 against socket frame 10. Release of processor 16 from adhesive 28 is managed by selection of an adhesive that has a desired retention force to maintain processor 16 coupled with load plate 12 until sufficient manual force is applied to ensure that inadvertent release does not occur.